

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Previously Presented) A socket for a semiconductor device, comprising:  
a socket body having a semiconductor device placement section for selectively accommodating a semiconductor device for electrical connection with contact terminals, said semiconductor device being one of a plurality of semiconductor devices having contour dimensions different from one another;

a pressing member having a touch portion brought in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals, said pressing member being driven by a pressing member driving mechanism in accordance with the attachment or detachment of said semiconductor device relative to said semiconductor device placement section, for holding said semiconductor device in said semiconductor device placement section; and

wherein, when said pressing member driving mechanism moves said touch portion of said pressing member to a position in which said touch portion of said pressing member does not contact said semiconductor device upon the attachment or detachment of said semiconductor device, a portion of said pressing member is bulged outwardly from an end of said socket body via an opening of said socket body.

2. (Previously Presented) A socket for a semiconductor device, comprising:  
a socket body having a semiconductor device placement section for selectively accommodating a semiconductor device for electrical connection with contact terminals,

said semiconductor device being one of a plurality of semiconductor devices having contour dimensions different from one another;

a pressing member having a touch portion brought in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals, for holding said semiconductor device in said semiconductor device placement section; and

a cover member supported by said socket body in a movable manner for bringing said touch portion of said pressing member into contact with or away from said semiconductor device in accordance with the attachment or detachment of said semiconductor device relative to said semiconductor device placement section;

wherein, said cover member and said socket body have openings, respectively, so that when said cover member causes said touch portion of said pressing member to move to a position in which said touch portion of said pressing member does not contact said semiconductor device, a portion of said pressing member is bulged outwardly from an end of said socket body via one or more of the openings of the socket body.

3. (Previously Presented) A socket for a semiconductor device as claimed in claim 1, wherein

said pressing member is a first pressing member, said first pressing member having a first proximal end supported in a moveably rotational manner at one end of said socket body, said touch portion is a first touch portion and is coupled to said first proximal end, and the movement of said first proximal end causes said first touch

portion to contact said semiconductor device so that said semiconductor device is pressed toward said contact terminals, the socket further comprising:

a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, said second pressing member having a second proximal end supported in a moveably rotational manner at another end of said socket body, said second pressing member having a second touch portion coupled to said second proximal end, wherein

the movement of said second proximal end causes said second touch portion to contact said semiconductor device so that said semiconductor device is pressed toward said contact terminals.

4. (Currently Amended) A socket for a semiconductor device comprising:

a socket body having a semiconductor device placement section for selectively accommodating a semiconductor device for electrical connection with contact terminals, said semiconductor device being one of a plurality of semiconductor devices having contour dimensions different from one another;

a first pressing member having a first touch portion brought in contact with said semiconductor device and pressing said semiconductor device toward said contact terminals, said pressing member being driven by a pressing member driving mechanism in accordance with the attachment or detachment of said semiconductor device relative to said semiconductor device placement section, for holding said semiconductor device in said semiconductor device placement section;

a second pressing member for holding said semiconductor device in said semiconductor device placement section in association with said first pressing member, and

wherein, when said pressing member driving mechanism moves said first touch portion of said pressing member to a position in which said first touch portion of said pressing member does not contact said semiconductor device upon the attachment or detachment of said semiconductor device, a portion of said first pressing member is bulged outwardly from an end of said socket body via an opening of said socket body, said first pressing member has a first proximal end supported in a moveably rotationally manner at one end of said socket body, [[and]]

said second pressing member has a second proximal end supported in a moveably rotationally manner at another end of said socket body and a touch portion in contact with said semiconductor device so that said semiconductor device is pressed toward said contact terminals, and

said second pressing member has a recess for allowing a portion of said first pressing member to enter.

Claims 5-11 (Cancelled).